Parameter	Symbol	Rating	Unit
Peak pulse power (t_p = 8/20 s)	P_K	420	W
Peak pulse current (t_p = 8/20 s)	I_{PP}	7	A
ESD according to IEC61000-4-2 air discharge	V_{ESD}	±30	KV
ESD according to IEC61000-4-2 contact discharge		±30	
Junction temperature	T_J	125	Ņ
Storage temperature	T_{STG}	-55~+150	

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Reverse maximum working voltage	V_{RWM}				¤ 36	V
Reverse leakage current	I_R	V_{RWM} = ¤ 36V			100	nA
Reverse breakdown voltage[1)]	V_{BR}	I_T = 1mA	36			V
Clamping voltage [2)]	V_C	I_{PP} = 1A t_p = 8/20 s		46	48	V
		I_{PP} = 7A t_p = 8/20 s		75	77	V
		V_{ESD}=8KV [3)]		65		V
Junction capacitance	C_J	V_R = 0V f = 1MHz		15	20	pF
Clamping voltage[4)]	V_{CL}	IPP = 16A tp = 100ns		60		V
Dynamic resistance[4)]	R_{DYN}			0.22		

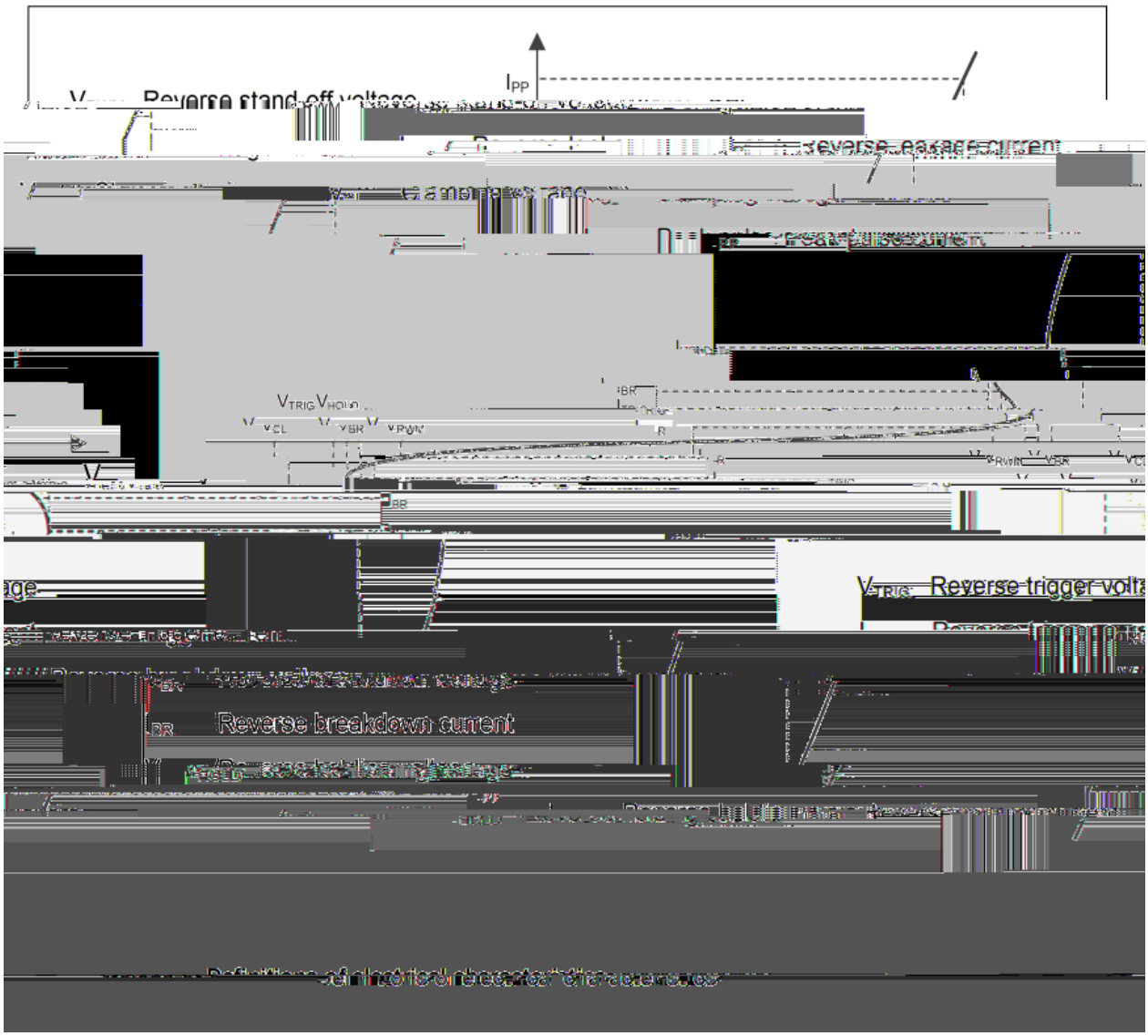
Notes:

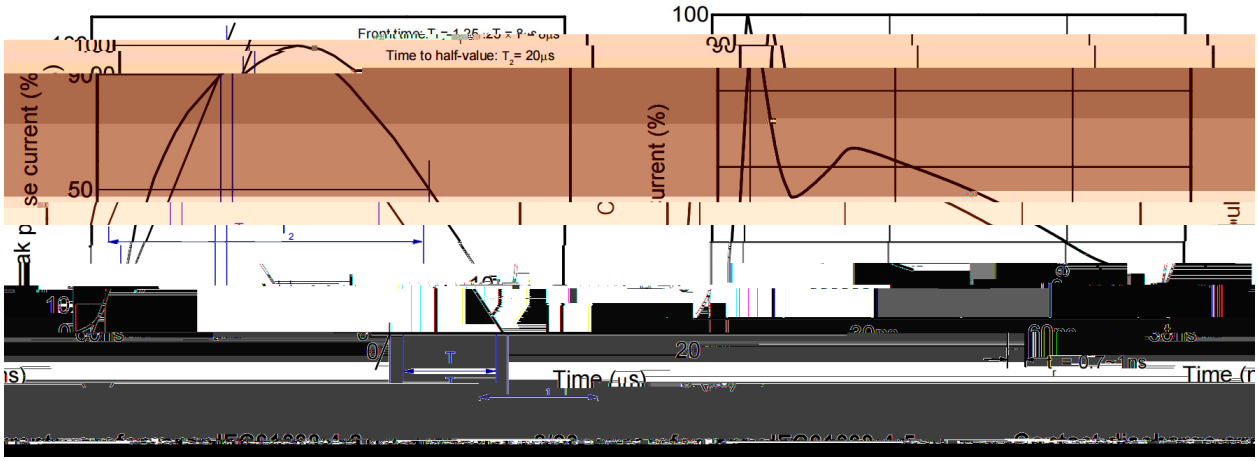
1) V_{BR} is measured with a pulse test current IT at an ambient temperature of 25 .

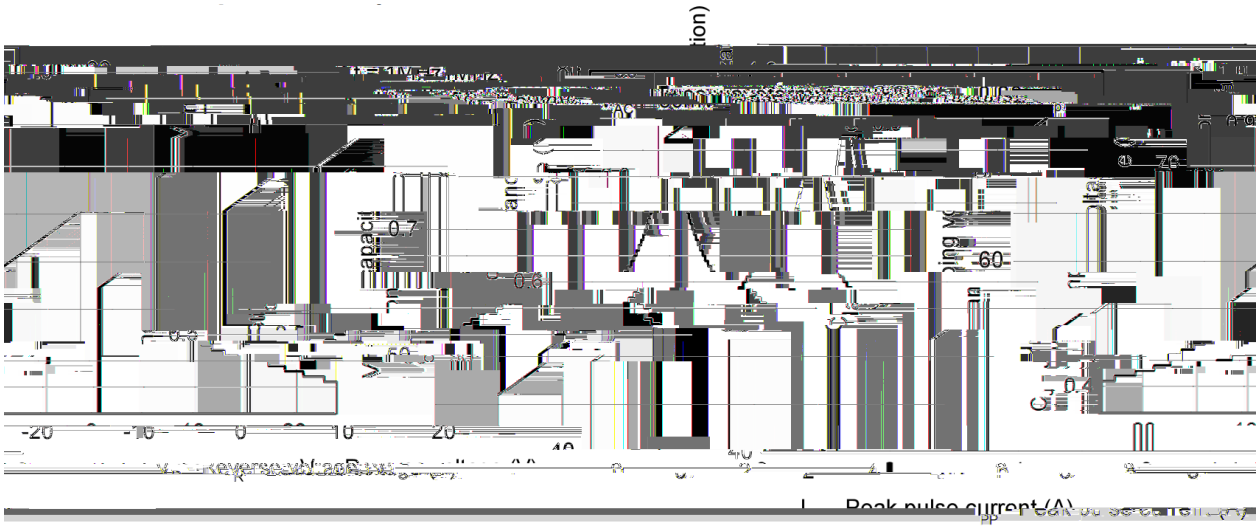
2) Non-repetitive current pulse, according to IEC61000-4-5.

3) Contact discharge mode, according to IEC61000-4-2.

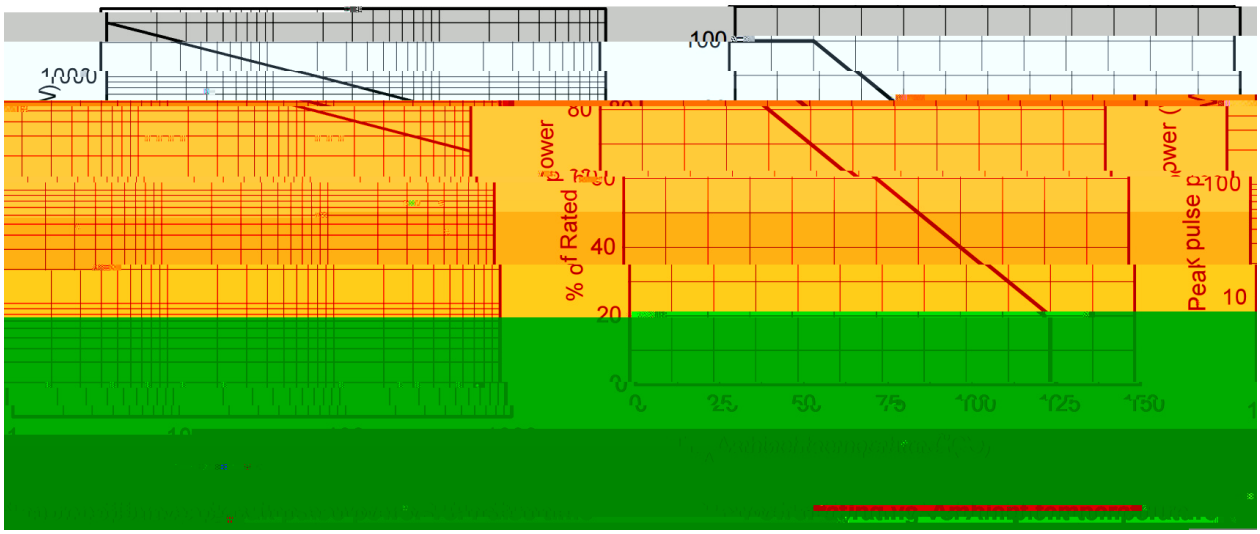
4)TLP parameter: Z0 = 50 , tp = 100ns, tr = 2ns, averaging window from 60ns to 80ns. RDYN is calculated from 4A to 16A.

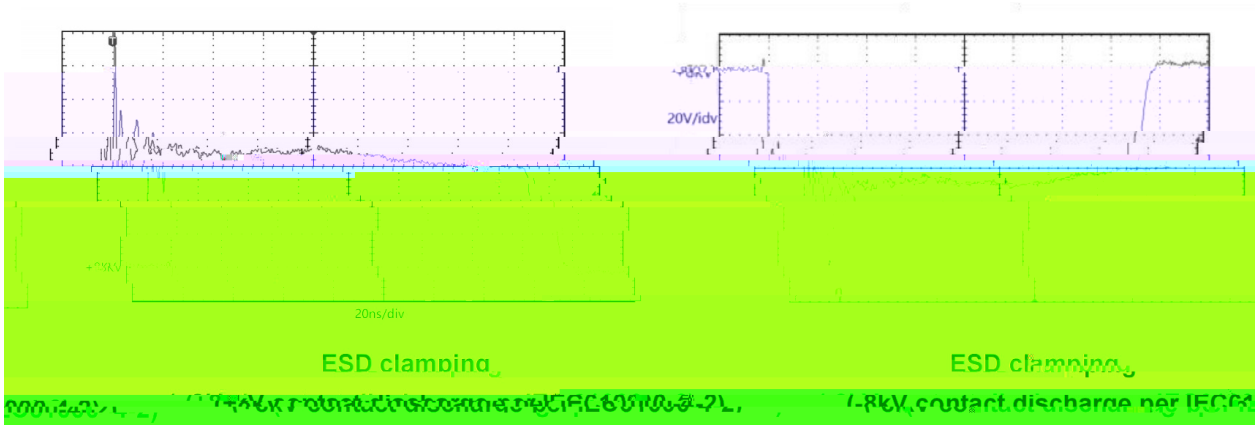

Ipp
Reverse breakdown current

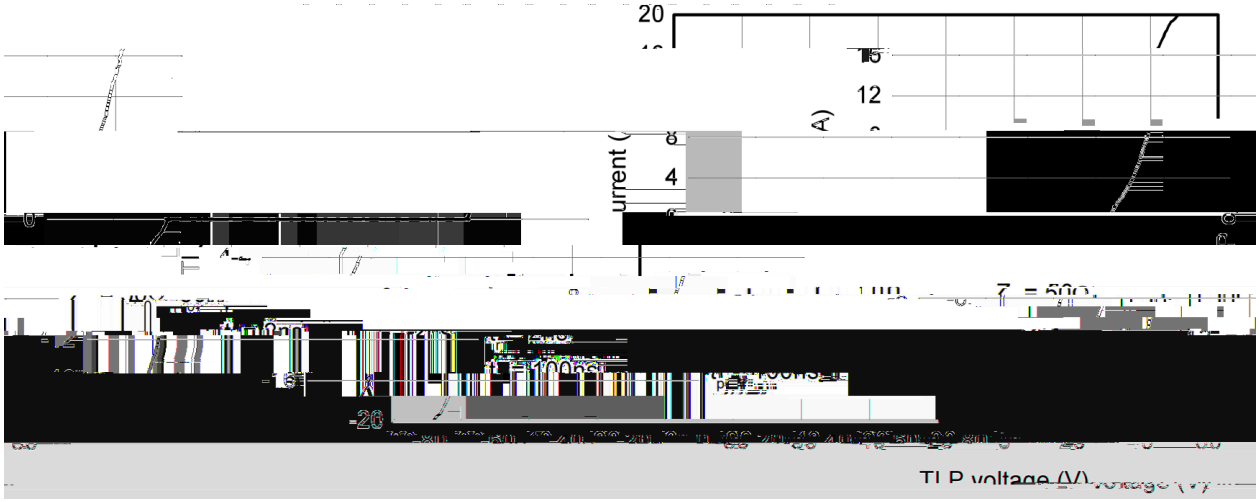




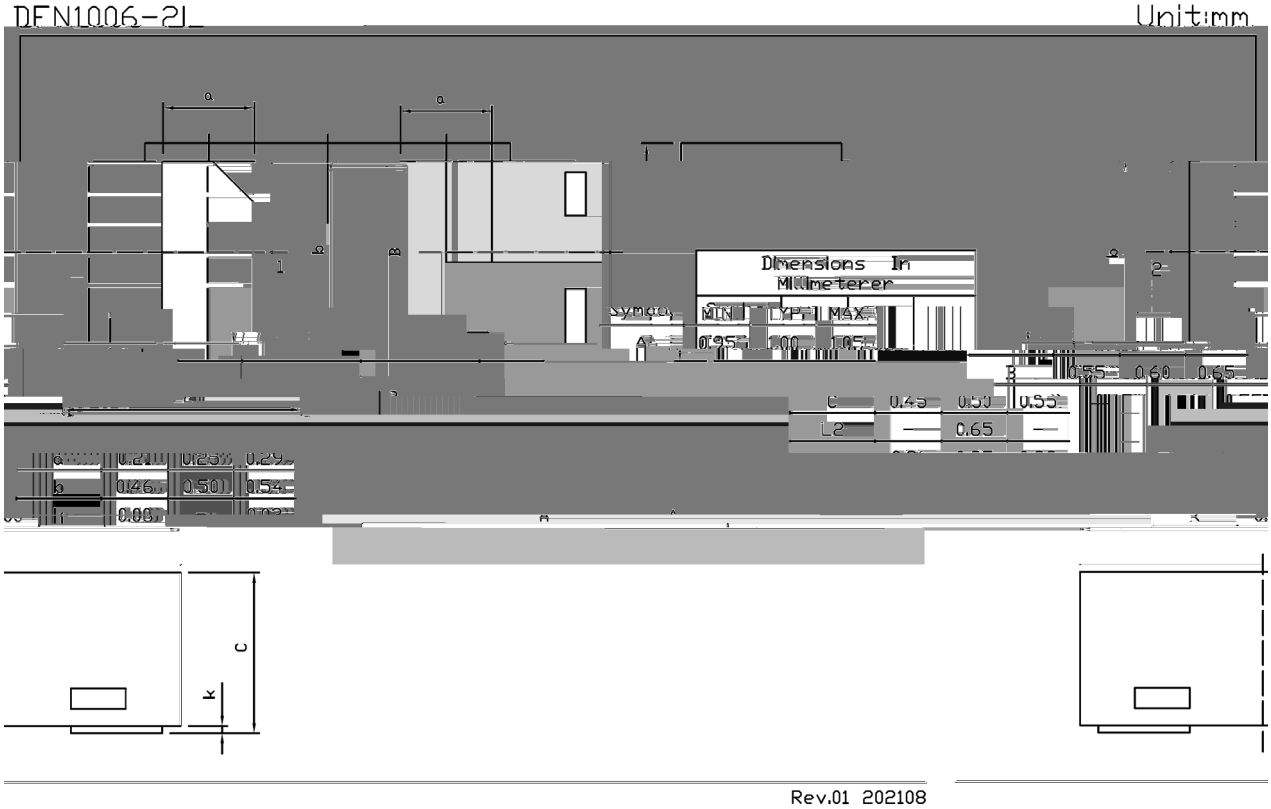
se current | Capacitance vs. Reverse voltage | Clamping voltage vs. Peak puls




20ns/div
20V/div
ESD clamping
ESD clamping


20
12
4
TLP voltage (V)

DFN1006-2L Unit:mm



Rev.01 202108

Temperature Profile for IR Reflow Soldering(Pb-Free)

Note:

1 150 180 60 90sec;

2 245±5 5±0.5sec;

3 2 10 /sec.

1.Preheating:150~180 , Time:60~90sec.

2.Peak Temp.:245±5 , Duration:5±0.5sec.

3. Cooling Speed: 2~10 /sec.

260±5 10±1 sec. Temp.:260±5 Time:10±1 sec

/ REEL

Package Type	Units	Dimension	(unit mm³)